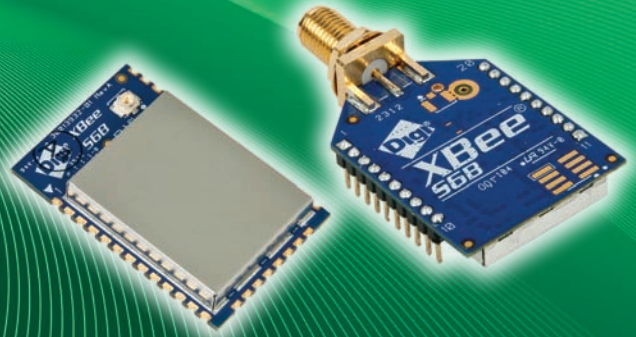


XBee® Wi-Fi

Embedded Wi-Fi Module for OEMs

Embedded Wi-Fi modules provide ultra low-power 802.11b/g/n communications in the flexible XBee hardware and software footprint.



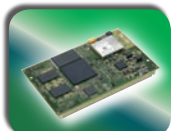
Overview

XBee Wi-Fi embedded RF modules provide simple serial to IEEE 802.11 connectivity. By bridging the low-power/low-cost requirements of wireless device networking with the proven infrastructure of 802.11, the XBee Wi-Fi creates new wireless opportunities for energy management, process and factory automation, wireless sensor networks, intelligent asset management and more. Featuring easy provisioning methods and native Device Cloud by Etherios™ connectivity, XBee Wi-Fi modules give developers the fastest IP-to-device and device-to-cloud capability possible. Focused on the rigorous requirements of these wireless device networks, the module gives developers IP-to-device and device-to-cloud capability.

XBee modules offer developers tremendous flexibility and are available in surface mount and through-hole form factors. The XBee Wi-Fi shares a common footprint with other XBee modules. This allows different XBee technologies to be drop-in replacements for each other.

As a member of the XBee family, the XBee Wi-Fi combines hardware with software for a complete modular solution. XBee Wi-Fi modules are designed to communicate with access points in existing 802.11 infrastructures. Developers can use AT and API commands for advanced configuration options.

Related Products



Wi-Fi System-on-Modules



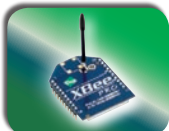
Wi-Fi Modules



Device Cloud Solutions



Wireless Serial Servers

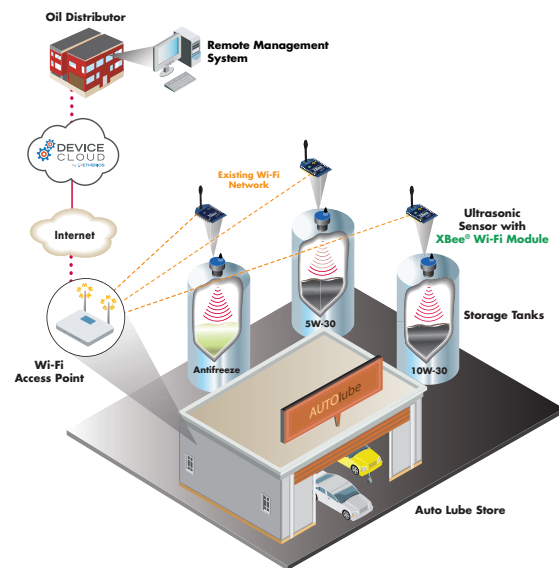


XBee Modules



Development Kits

Application Highlight



Features/Benefits

- Native Device Cloud integration for data acquisition and device management
- Hardware and software complete module easily joins existing 802.11 b/g/n (Wi-Fi) infrastructures
- Common XBee footprint allows OEMs to support a variety of wireless protocols
- Flexible SPI and UART serial interfaces
- Available in Surface Mount and Through-Hole form factors
- Support for low-power sleeping applications with $<6 \mu A$ power-down current
- Over-the-air data rates up to 72 Mbps
- Simple provisioning methods including Soft AP and Wi-Fi Protected Setup (WPS)



Platform		XBee® Wi-Fi (S6B)
Features		
Serial Data Interface	UART up to 1 Mbps, SPI up to 6 Mbps	
Configuration Method	API or AT commands	
Frequency Band	ISM 2.4 GHz	
ADC Inputs	4 (12-bit)	
Digital I/O	10	
Form Factor	Through-Hole, Surface Mount	
Antenna Options	Through-Hole: PCB (Embedded), U.FL, RPSMA, Integrated Wire SMT: PCB (Embedded), U.FL, RF Pad	
Operating Temperature	-30° C to +85° C	
Dimensions (L x W)	Through-Hole: 0.960 in x 1.297 in (2.438 cm x 3.294 cm) SMT: 0.87 in x 1.33 in x 0.12 in (2.20 cm x 3.40 cm x 0.30 cm)	
Networking and Security		
Security	WPA-PSK,WPA2-PSK and WEP	
Channels	13 channels	
Wireless LAN		
Standard	802.11b/g/n	
Data Rates	1 Mbps to 72 Mbps	
Modulation	802.11b: CCK, DSSS 802.11g/n: OFDM with BPSK, QPSK, 16-QAM, 64-QAM	
Transmit Power	Up to +16 dBm	
Receiver Sensitivity	-93 to -71 dBm	
Power Requirements		
Supply Voltage	3.14 - 3.46 VDC	
Transmit Current	Up to 309 mA	
Receive Current	100 mA	
Power-Down Current	<6 µA @ 25° C	
Regulatory Approvals		
FCC (USA)	Yes	
IC (Canada)	Yes	
CE/ETSI (Europe)	Yes	
C-TICK (Australia)	Yes	
Telec (Japan)	Yes	
Anatel (Brazil)	Pending	

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Наши преимущества:

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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